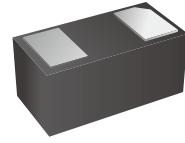


1-Line Ultra Small Bi-directional TVS Diode

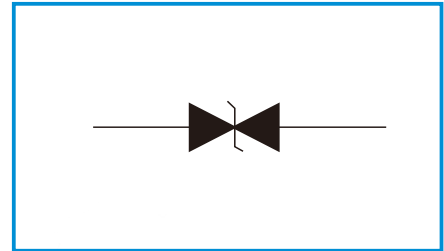
Features

- Ultra small package: 1.0x0.6x0.5mm
- Protects one data or power line
- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- 2-pin leadless package
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: ±30kV
 - Contact discharge: ±30kV
 - IEC61000-4-5 (Lightning) 15A (8/20µs)
- RoHS Compliant



DFN1006-2

Functional Diagram



Mechanical Data

- Package: DFN1006-2 (1.0×0.6×0.5mm)
- Case Material: “Green” Molding Compound.
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram Below
- Marking :B4

Applications

- Cellular Handsets and Accessories
- Personal Digital Assistants
- Notebooks and Handhelds
- Portable Instrumentation
- Digital Cameras
- Peripherals
- Audio Players
- Keypads, Side Keys, LCD Displays

Absolute Maximum Ratings (T_{amb}=25°C unless otherwise specified)

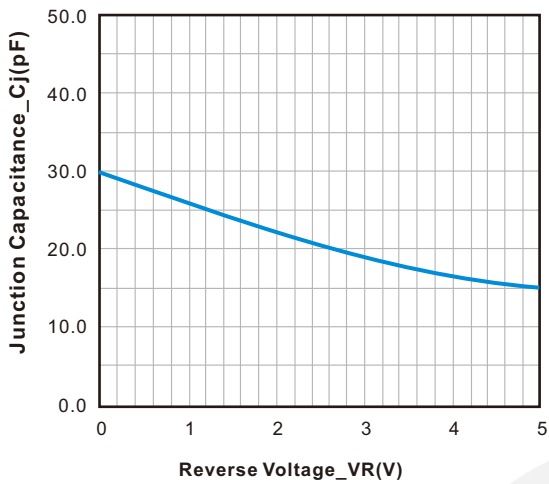
Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20µs)	Ppk	200	W
Peak Pulse Current (8/20µs)	Ipp	15	A
ESD per IEC 61000-4-2 (Air)	VESD	±30	kV
ESD per IEC 61000-4-2 (Contact)		±30	
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

Electrical Characteristics (TA=25°C unless otherwise specified)

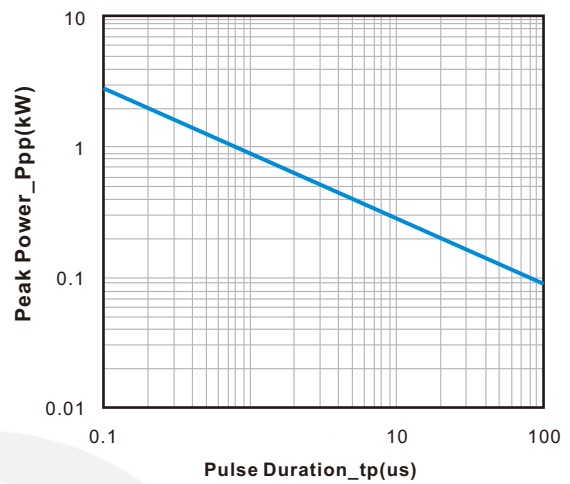
Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	VRWM			5	V	
Breakdown Voltage	VBR	6			V	IT = 1mA
Reverse Leakage Current	IR			0.2	μA	VRWM = 5V
Clamping Voltage	VC			8	V	I _{PP} = 1A (8 x 20μs pulse)
Clamping Voltage	VC			14	V	I _{PP} = 15A (8 x 20μs pulse)
Junction Capacitance	CJ		30	50	pF	VR = 0V, f = 1MHz



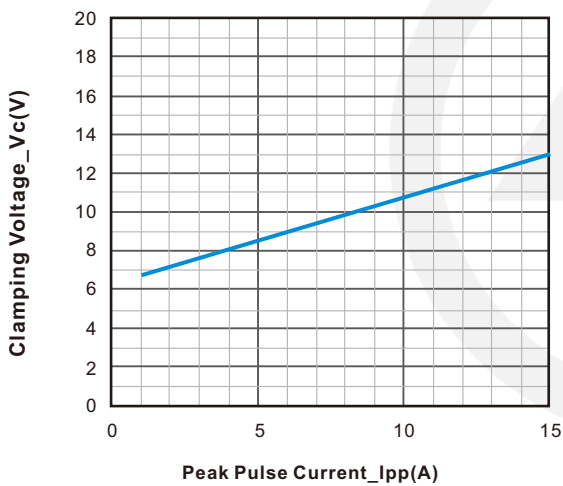
Characteristic Curves



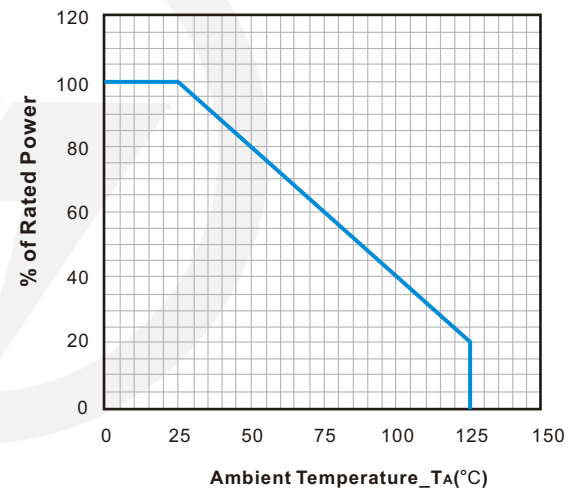
Junction Capacitance vs. Reverse Voltage



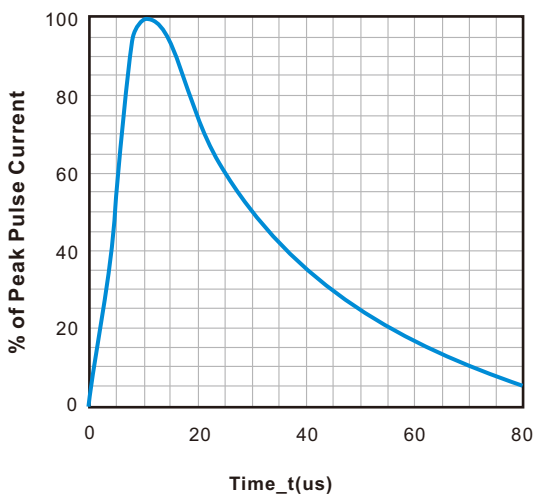
Peak Pulse Power vs. Pulse Time



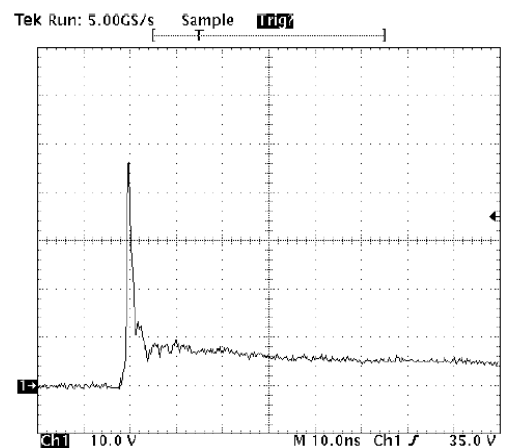
Clamping Voltage vs. Peak Pulse Current



Power Derating Curve



8 X 20µs Pulse Waveform



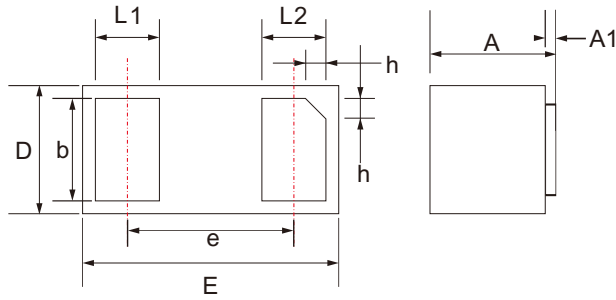
Note: Data is taken with a 10x attenuator

ESD Clamping Voltage

8 kV Contact per IEC61000-4-2

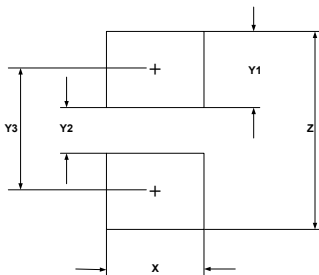
DFN1006-2 Package Outline

Unit: mm



SYMBOL	DIMENSIONS	
	MIN.	MAX.
D	0.550	0.650
E	0.950	1.050
L1	0.200	0.300
L2	0.200	0.300
b	0.450	0.550
e	0.650 TYP.	
A	0.450	0.550
A1	0.000	0.050
h	0.070	0.170

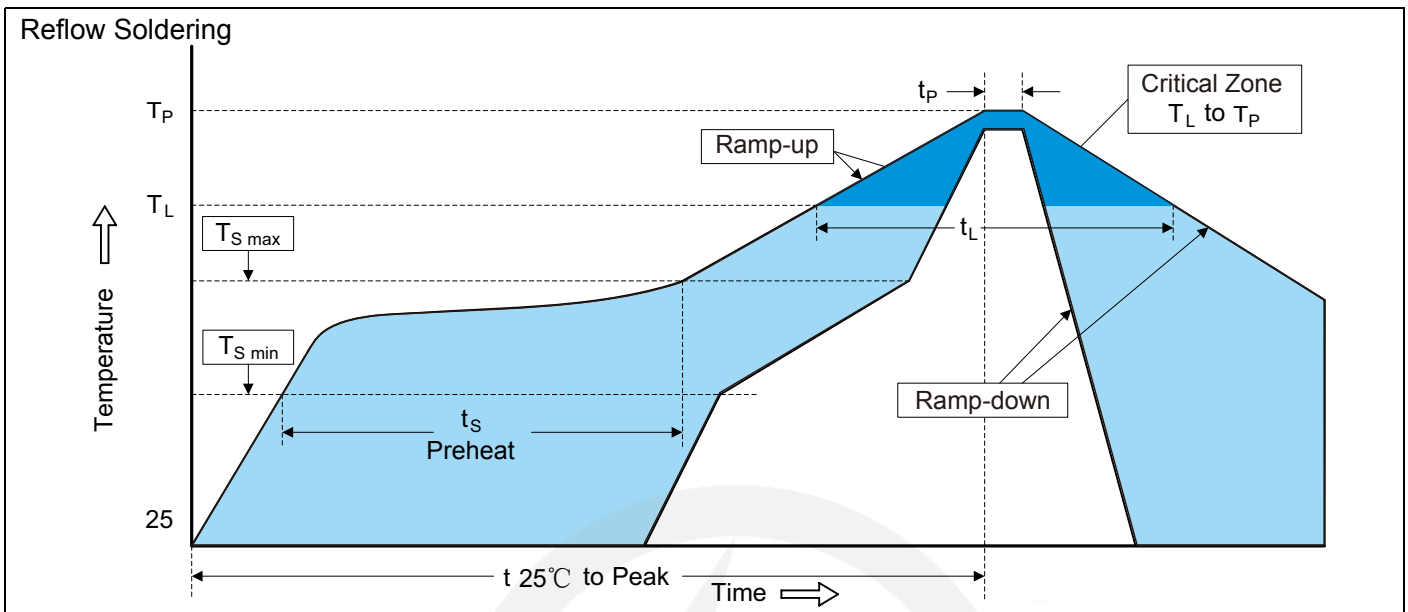
DFN1006-2 Suggested Pad Layout



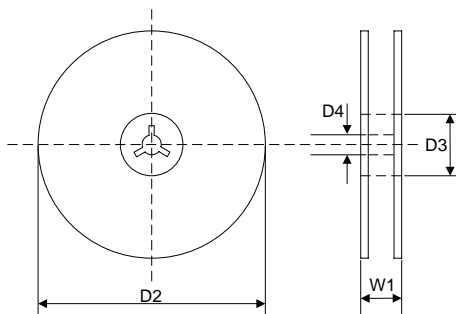
SYM	DIMENSIONS
	MILLIMETERS
X	0.60
Y1	0.50
Y2	0.30
Y3	0.80
Z	1.30

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purpose only.

Recommended Soldering Conditions

Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

7" Reel


D2	$\Phi 178.0 \pm 2.0$
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D3	$\Phi 50.0 \text{ Min.}$
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D4	$\Phi 13.0 \pm 0.5$
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W1	16.0 ± 2.0
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Quantity: 10000PCS